

**APPARATUS WITH RESOLUTION ENHANCEMENT FEATURE FOR
IMPROVING ACCURACY OF CONVERSION OF REQUIRED CHEMICAL
MECHANICAL POLISHING PRESSURE TO FORCE TO BE APPLIED BY
POLISHING HEAD TO WAFER**

5

ABSTRACT OF THE DISCLOSURE

CMP systems move a polishing pad relative to a wafer and a retainer ring and implement instructions to apply required pressure to the wafer for CMP operations.

Accuracy of computations of the pressures, and of conversion of the pressure to force, is

10 improved without use of high resolution components, such as high resolution digital devices, using both digital and analog operations, and by converting values of required pressure or force from one set of units to a second set of units and then back to the first set of units. A quantization process is performed using data processed by average resolution digital devices. The process transfers both pressure/force scale and pressure/force set point
15 data between separate processors to obtain computed values of pressure and force having acceptable accuracy, eliminating quantization errors are eliminated or significantly reduced.